

ELECTROSTATIC CHUCK

ABSTRACT OF THE DISCLOSURE

Disclosed herein is an electrostatic chuck having a holding surface for holding a wafer with a tape attached to one side of the wafer in the condition where the tape is in contact with the holding surface. The electrostatic chuck includes a disk-shaped member having a plurality of fine holes communicating with a vacuum source, the fine holes being exposed to the holding surface, a plurality of asperities formed on the holding surface and connected to the fine holes, and an electrode embedded in the disk-shaped member. When the vacuum source is operated to produce a vacuum on the holding surface through the fine holes and thereby hold the wafer through the tape on the holding surface under suction, the asperities formed on the holding surface function as a suction passage communicating with the fine holes.

Figure 4A